### LINEAR IC

# R-2R TYPE 8-BIT D/A CONVERTER WITH OPERATIONAL AMPLIFIER OUTPUT BUFFERS

## MB88346B

#### DESCRIPTION

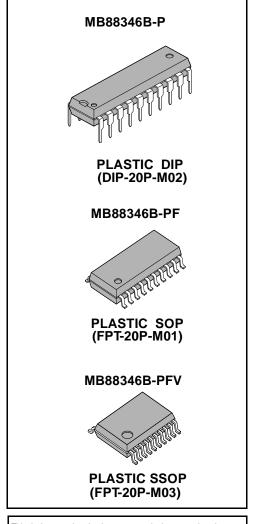
The Fujitsu MB88346B is an R-2R type 8-bit resolution digital-to-analog converter (DAC), designed for interface with a wide range of general 4-bit and 8-bit microcontrollers including Fujitsu's MB88200 family, MB8850 family, and MB88500 family 4-bit single-chip microcontrollers.

The MB88346B has an 8-bit x 12-channel D/A converter with operational amplifier output buffers. Digital data are input serially by individual channel units. The loaded digital data are converted into analog DC voltages by the D/A converter in 20  $\mu s$  settling time. Also, the MB88346B has operational amplifier output buffers. These operational amplifier output buffers are connected to each channel of the D/A converter, and provide high current drive capability. The MB88346B is suitable for electronic volumes and replacement for potentiometers for adjustment, in addition to normal D/A converter applications.

#### **■ FEATURES**

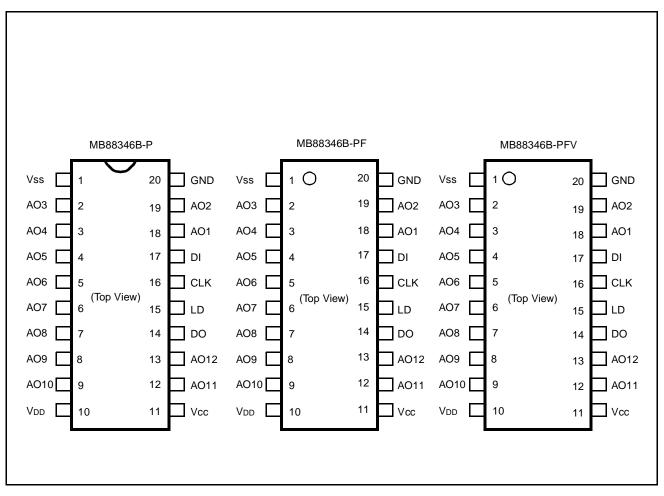
- · Conversion method: R-2R resistor ladder
- 8-bit x 12-channel D/A converter with operational amplifier output buffers
- Max. 2.5MHz Serial data input
- Serial data output for cascade connection
- Max. 20 μs DAC output settling time
- Max. +1.0/-1.0 mA analog output sink/source current
- Two separate power supply/ground lines for MCU interface block/ operational amplifier output buffer block and D/A converter block
- Pin compatible with MB88341
- Single +5V power supply
- Wide operating temperature range: -20°C to +85°C
- Silicon-gate CMOS process
- Three package options:
   20-pin plastic DIP (Suffix: -P), 20-pin plastic SOI

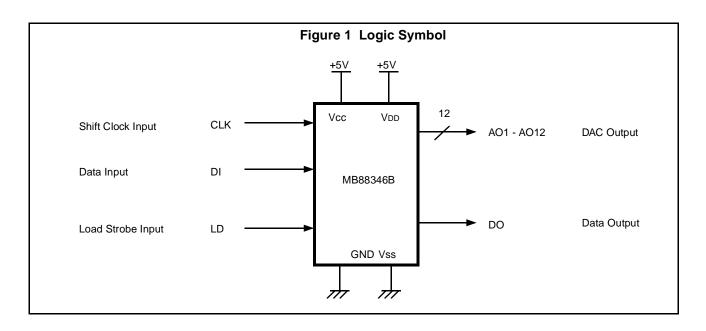
20-pin plastic DIP (Suffix : -P), 20-pin plastic SOP (Suffix : -PF), 20-pin plastic SSOP(Suffix : -PFV)



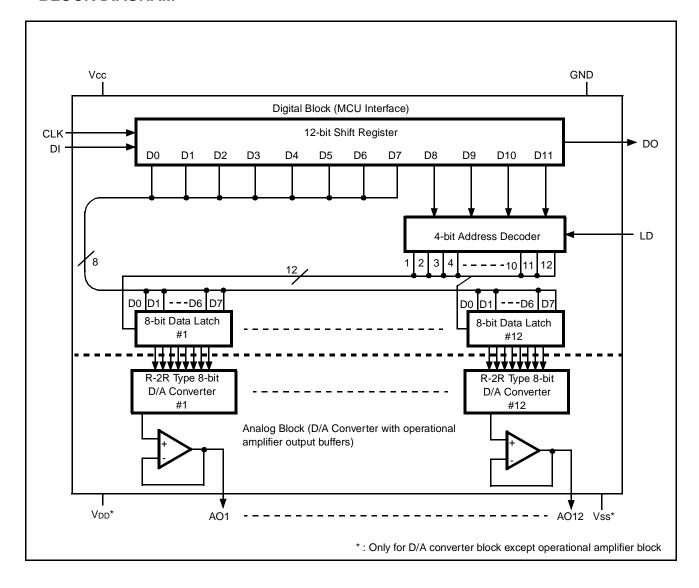
This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

#### **■ PIN ASSIGNMENT**





#### **■ BLOCK DIAGRAM**



#### **■ PIN DESCRIPTION**

PIN ASSIGNMENT and Tableshow the pin assignment and pin description of the MB88346B.

**Table 1 Pin Description** 

Symbol	Pin No.	Туре	Name & Function				
Power Su	pply						
Vcc	11	-	+5V DC power supply pin for the digital block (MCU interface) and operational amplifier output buffers.				
GND	20	-	Ground pin for the digital block (MCU interface) and operational amplifier output buffers.				
VDD	10	-	DC power supply pin for the analog block (D/A converter) except operational amplifier output buffers.				
Vss	1	-	Ground pin for the analog block (D/A converter) except operational amplifier output buffers.				
Control Ir	put						
CLK	16	1	Shift clock input to the internal 12-bit shift register: At the rising edge of CLK data on the DI pin is shifted into the LSB of the shift register and contents of the shift register are shifted right (to the MSB).				
LD	15	I	Load strobe input for a 12-bit address/data: A high level on the LD pin latches a 4-bit address (upper 4 bits: D11 to D8) of the internal 12-bit shift register into the internal address decoder, and writes 8-bit data (lower 8 bits: D7 to D0) of the shift register into an internal data latch selected by the latched address.				
Data Inpu	t/Output						
DI	17	I	Serial address/data input to the internal 12-bit shift register: The address/data format is that upper 4 bits (D11 to D8) indicate an address and lower 8 bits (D7 to D0) indicate data. The D11 (MSB) is the first-in bit and D0 (LSB) is the last-in bit.				
Do	14	0	Serial address/data output from the internal 12-bit shift register: This is an output pin of the MSB bit data of the 12-bit shift register. This pin allows a cascade connection of the device.				
DAC Outp	out						
AO1 AO2 AO3 AO4 AO5 AO6 AO7 AO8 AO9 AO10 AO11 AO12	18 19 2 3 4 5 6 7 8 9 12 13	0	8-bit resolution D/A converter outputs : 12 channels of DAC outputs (AO1 to AO12) are provided.  Each output channel has an operational amplifier output buffer for analog output data.				

#### **■ FUNCTIONAL DESCRIPTION**

#### **OVERVIEW**

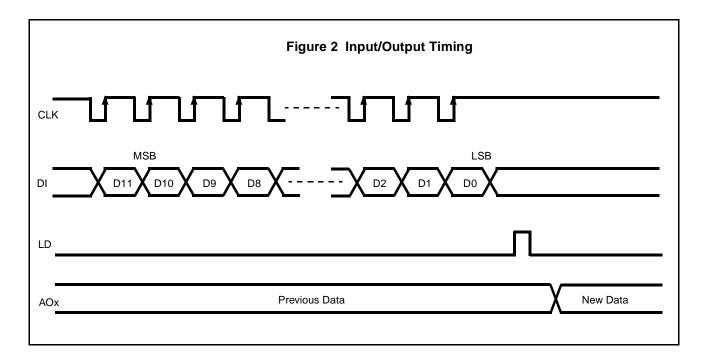
The MB88346B is an R-2R resistor ladder type, 8-bit resolution digital-to-analog converter (DAC) device. The MB88346B has 12 channels of D/A converters with operational amplifier output buffers. 8-bit digital data are loaded into internal data latches by individual DAC channel units. The loaded digital data are converted into analog DC voltages through the internal D/A converter in max. 20  $\mu$ s settling time. And the analog DC voltages source/sink the output current through the operational amplifier output buffers. For cascade connection, a serial data output is provided.

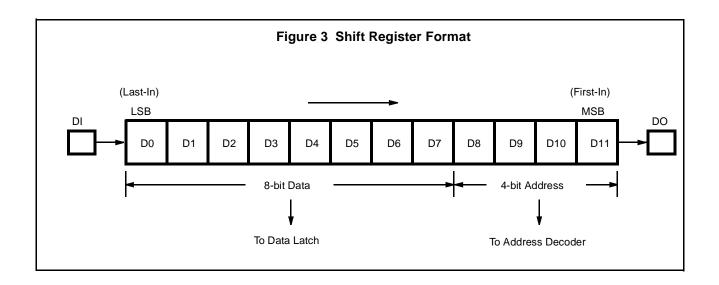
#### **DEVICE CONFIGURATION**

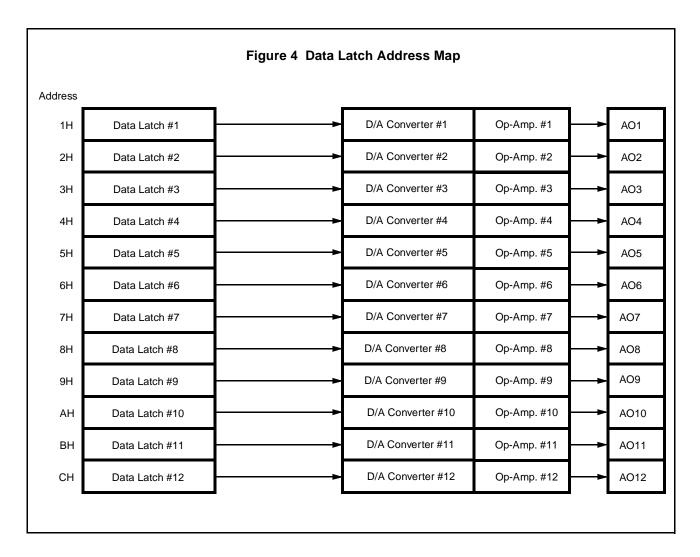
As illustrated in BLOCK DIAGRAM, the MB88346B device is composed by the digital block (MCU interface) and analog block (D/A converter with operational amplifier output buffers). The digital block consists of a 12-bit shift register, a 4-bit address decoder, and 12-channels of 8-bit data latches. The analog block includes 12 channels of 8-bit D/A converters with operational amplifier output buffers connecting to the data latches. For electrically stable operation the power supply and ground lines are separate between the digital block (MCU interface) and operational amplifier output buffers, and analog block except operational amplifier output buffers.

#### **DEVICE OPERATION**

Figure 2 shows the input/output timing. A 12-bit address/data is serially input into the shift register through the DI pin synchronously with the rising edge of CLK. The format of the shift register is shown in Figure 3. The lower 8 bits (D7 to D0) are data bits to be converted, and the upper 4 bits are address bits (D11 to D8) to select a data latch to be written. A high level on the LD pin loads the address decoder with the 4-bit address to select a data latch, and writes the 8-bit data into a selected data latch. Figure 4 shows the data latch address map, and Table, address decoding. 8-bit data written into individual data latches are converted into analog DC voltages, dividing the supply voltage |VDD-Vss| through R-2R resistor ladders of D/A converters. The operational amplifier output buffers at individual D/A converter outputs can source up to 1.0 mA of the output current. Figure 5 shows a configuration of the R-2R resistor ladder D/A converter with operational amplifier, and Table 3analog DC voltages corresponding to each digital data.







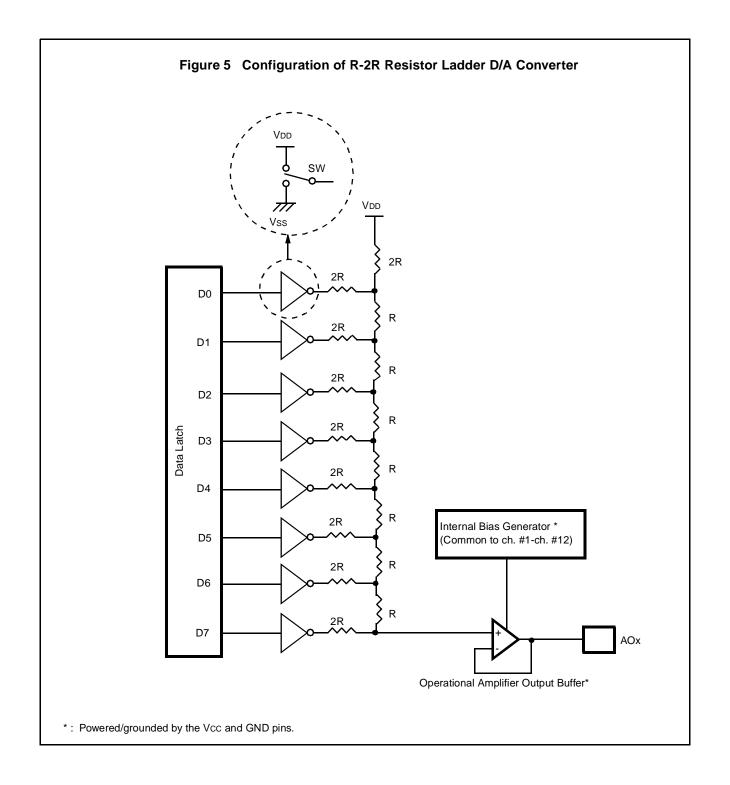
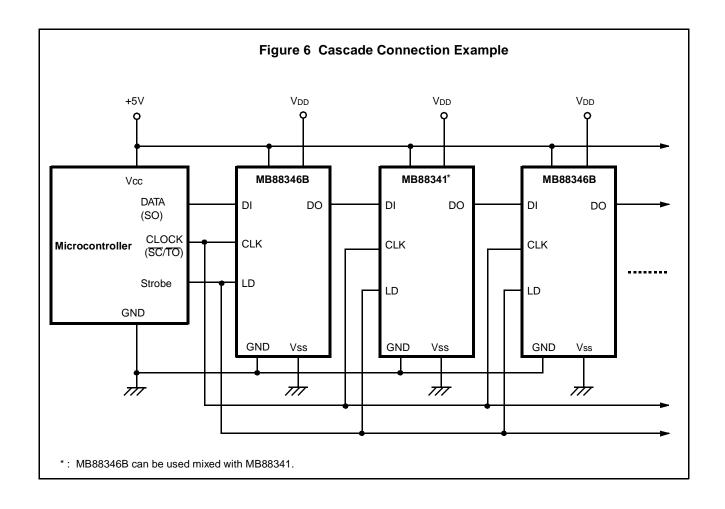


Table 2 Address Decoding

	Add	ress	Data Latch Selected	
D8	D9	D10	D11	MB88346B
0	0	0	0	Deselected
0	0	0	1	Data Latch #1
0	0	1	0	Data Latch #2
0	0	1	1	Data Latch #3
0	1	0	0	Data Latch #4
0	1	0	1	Data Latch #5
0	1	1	0	Data Latch #6
0	1	1	1	Data Latch #7
1	0	0	0	Data Latch #8
1	0	0	1	Data Latch #9
1	0	1	0	Data Latch #10
1	0	1	1	Data Latch #11
1	1	0	0	Data Latch #12
1	1	0	1	Deselected
1	1	1	0	Deselected
1	1	1	1	Deselected

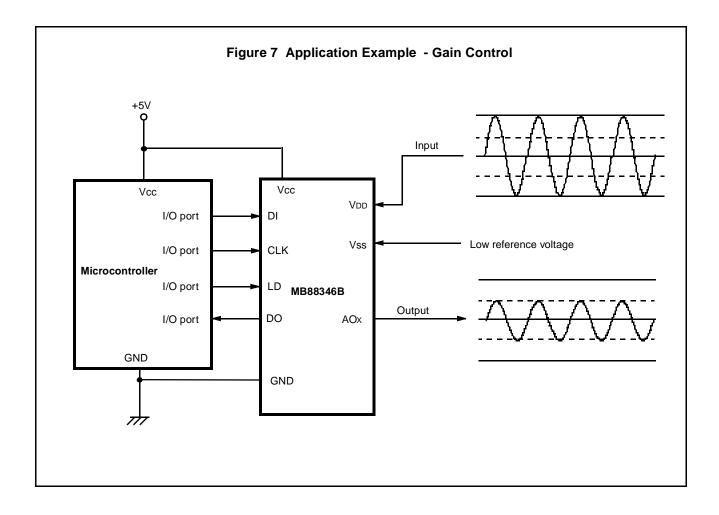
**Table 3 Data Conversion** 

			Da	DAC Output Level				
D7	D6	D5	D4	D3	D2	D1	D0	AOx
0	0	0	0	0	0	0	0	≈ Vss
0	0	0	0	0	0	0	1	≈ (VDD-VSS) x 1/255 + VSS
0	0	0	0	0	0	1	0	≈ (VDD-VSS) x 2/255 + VSS
0	0	0	0	0	0	1	1	≈ (VDD-VSS) x 3/255 + VSS
1	 	! ! !	 	! ! !	! ! !	 	! ! !	
1	1	1	1	1	1	1	0	≈ (VDD-VSS) x 254/255 + VSS
1	1	1	1	1	1	1	1	≈ VDD



#### ■ APPLICATION DESCRIPTION

The MB88346B is suitable for electronic volumes and replacement for adjustment potentiometers, in addition to normal D/A converter applications. Figure 7 illustrates application example for a gain control.



## ■ ELECTRICAL CHARACTERISTICS ABSOLUTE MAXIMUM RATINGS (See NOTE)

Parameter	Symbol		Rating		Unit	Condition	
rarameter	Зуппоп	Min Typ		Max	Onit	Condition	
Supply Voltage	Vcc	-0.3	-	7.0	V	Ta = +25°C	
Supply Voltage	VDD	-0.3	-	7.0	V	$GND = 0 \ V \ VDD \le Vcc,$	
Input Voltage	VIN	-0.3	-	Vcc+0.3	V	Ta = +25°C	
Output Voltage	Vout	-0.3	-	Vcc+0.3	V	GND = 0 V	
Power Dissipation	PD	-	-	250	mW		
Operating Ambient Temperature	Та	-20	-	+85	°C		
Storage Temperature	Tstg	-55	-	+150	°C		

NOTE: Permanent device damage may occur if the above ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol		Value	Unit	Condition		
Parameter	Syllibol	Min	Тур	Max	Onit	Condition	
Supply Voltage	Vcc	4.5	5.0	5.5	V	Vcc≥Vdd	
(for MCU Interface/OpAmp. Block)	GND	-	0	-	V		
Supply Voltage	Vcc	2.0	-	Vcc	V	VDD-VSS≥2.0V	
(for Analog Block*)	Vss	GND	-	VCC-2.0	V		
Analog Output Source Current	IAL	-	-	+1.0	mA		
Analog Output Sink Current	Іан	-	-	+1.0	mA		
Analog Output Load Capacitance for oscillation limit	CAL	-	-	1.0	μF		
Operating Ambient Temperature	Та	-20	-	+85	°C		

<sup>\*:</sup> Except operational amplifier output buffer block

#### **■ DC CHARACTERISTICS**

(Recommended operating conditions unless otherwise noted.)

#### **Digital Block (MCU Interface)**

Parameter	Symbol		Value	Unit	Condition		
raiametei	Syllibol	Min	Тур	Max	Oilit	Condition	
Active Supply Current (Vcc) *	Icc	-	2.5	4.5	mA	CLK = 1MHz, Unloaded	
Input Leakage Current (CLK, DI, and LD)	lilk	-10	-	+10	μΑ	V <sub>IN</sub> = 0 to Vcc	
Input Low Voltage (CLK, DI, and LD)	VIL	-	-	0.2∙Vcc	V		
Input High Voltage (CLK, DI, and LD)	VIH	0.5•Vcc	-	-	V		
Output Low Voltage (DO)	VOL	-	-	0.4	V	IOL = 2.5 mA	
Output High Voltage (DO)	Voн	Vcc-0.4	-	-	V	Ιοн = -400 μΑ	

<sup>\*:</sup> Including the supply current to the operational amplifier block

#### **Analog Block (D/A Converters with Operational Amplifier Output Buffers)**

Parameter	Symbol	Value			Unit	Condition
Farameter	Syllibol	Min	Тур	Max	Ollit	Condition
Supply Current (VDD) **	IDD	-	0.2	0.5	mA	Unloaded
Min. Analog Output Voltage 1 (AOx)	VAOL1	Vss	-	Vss+0.1	V	VDD=VCC, VSS=GND=0V Unloaded, Didital Data=#00
Min. Analog Output Voltage 2 (AOx)	VAOL2	Vss-0.2	Vss	Vss+0.2	V	VDD=VCC=5.0V, VSS=GND=0V IAL=+500μA, Digital Data=#00
Min. Analog Output Voltage 3 (AOx)	VAOL3	Vss	-	VSS+0.2	V	VDD=VCC=5.0V, VSS=GND=0V IAH=+500μA, Digital Data=#00
Min. Analog Output Voltage 4 (AOx)	VAOL4	Vss-0.3	Vss	Vss+0.3	V	VDD=VCC=5.0V, VSS=GND=0V IAL=+1.0mA, Digital Data=#00
Min. Analog Output Voltage 5 (AOx)	VAOL5	Vss	-	Vss+0.3	V	VDD=VCC=5.0V, VSS=GND=0V IAH=+1.0mA, Digital Data=#00
Max. Analog Output Voltage 1 (AOx)	VAOH1	VDD-0.1	-	VDD	V	VDD=VCC, VSS=GND=0V Unloaded, Digital Data=#FF
Max. Analog Output Voltage 2 (AOx)	VAOH2	VDD-0.2	-	VDD	V	VDD=VCC=5.0V, VSS=GND=0V IAL=+500μA, Digital Data=#FF
Max. Analog Output Voltage 3 (AOx)	VAOH3	VDD-0.2	VDD	VDD+0.2	V	V <sub>DD</sub> =VCC=5.0V, VSS=GND=0V IAH=+500μA, Digital Data=#FF

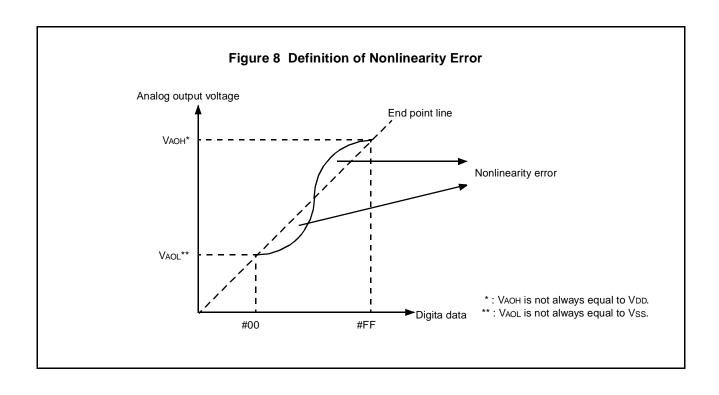
<sup>\*\*:</sup> Excluding the supply current to the operational amplifier block

Analog Block (D/A Converters with Operational Amplifier Output Buffers) - Continued

Parameter	Symbol		Value		Unit	Condition	
Farameter	Syllibol	Min	Тур	Max	Offic	Condition	
Max. Analog Output Voltage 4 (AOx)	VAOH4	VDD-0.3	-	VDD	V	VDD=VCC=5V, VSS=GND=0V, IAL=+1.0mA, Digital Data=#FF	
Max. Analog Output Voltage 5 (AOx)	VAOH5	VDD-0.3	VDD	VDD+0.3	V	VDD=VCC=5V, VSS=GND=0V, IAH=+1.0mA, Digital Data=#FF	
Resolution (AOx)	Res	-	8	-	bit	Monotonicity	
Differential Error* (AO <sub>x</sub> )	DE	-1.0	0	+1.0	LSB	Unloaded, VDD≤VCC-0.1V, VSS≥0.1V	
Nonlinearity Error** (AOx)	LE	-1.5	0	+1.5	LSB	Unloaded, VDD≤VCC-0.1V, VSS≥0.1V, See Figure 8.	

<sup>\*:</sup> The difference from the ideal increment value when the digital data is increased by 1 bit.

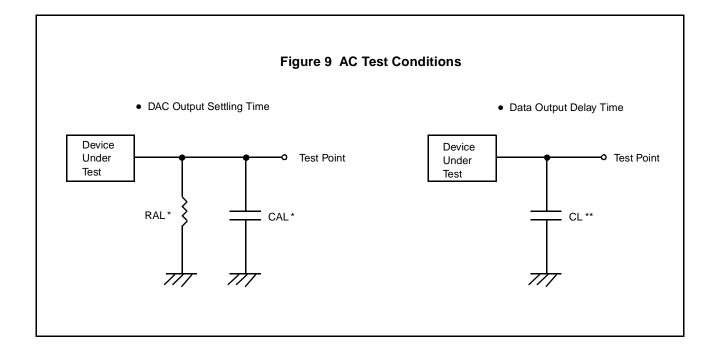
<sup>\*\*:</sup> The difference between the input-output curve for the straight line (ideal line) that connects the output voltage of the channel when #00 is set, and the output voltage when #FF is set.

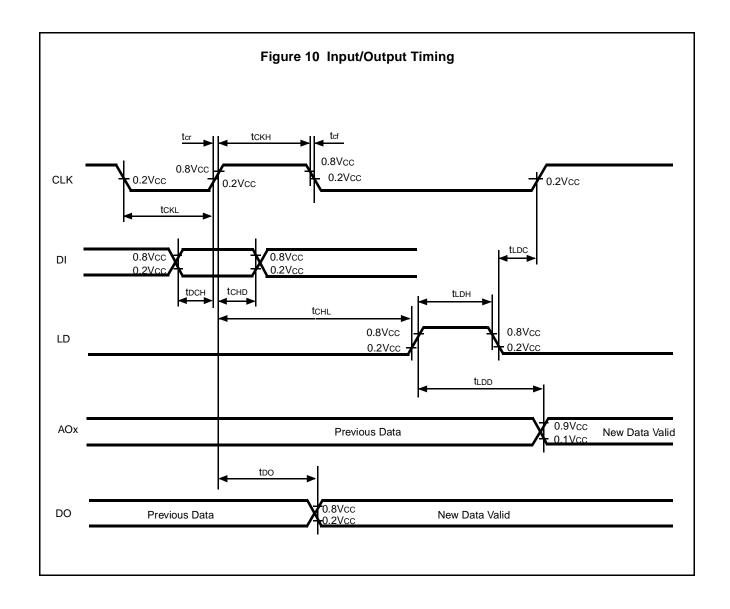


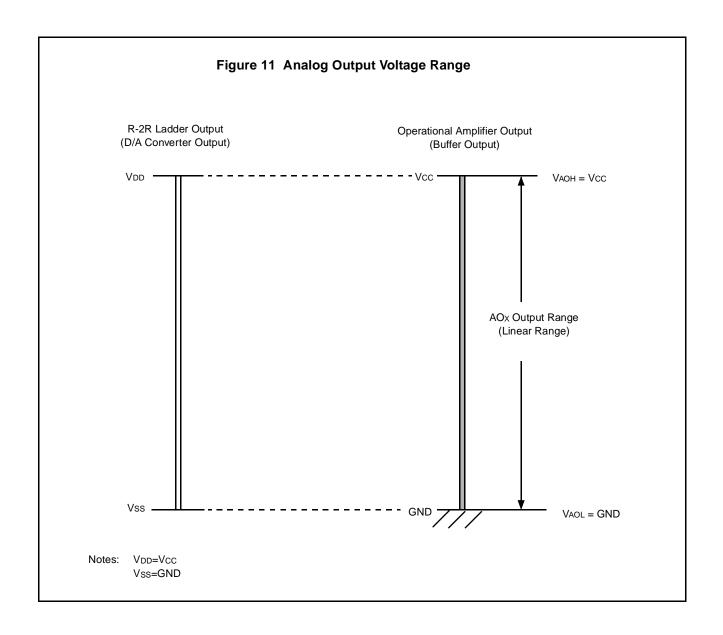
#### **■ AC CHARACTERISTICS**

(Recommended operating conditions unless otherwise noted.)

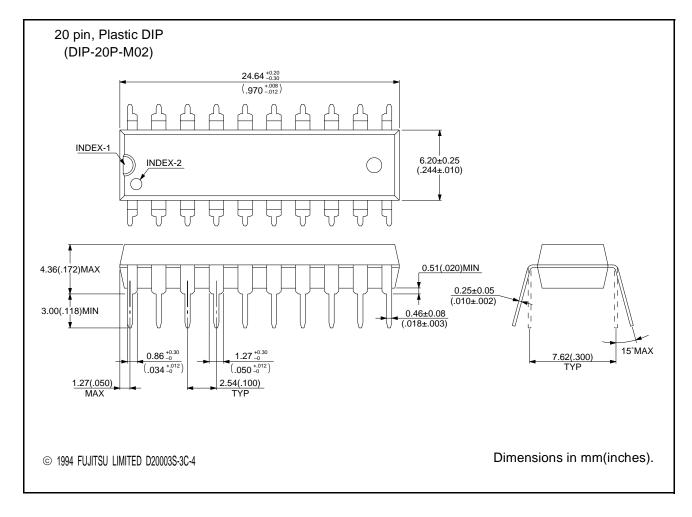
Parameter	Symbol	Va	lue	Unit	Condition
Parameter	Symbol	Min	Max	Offic	Condition
Clock Low Time	tCLK	200	-	ns	
Clock High Time	tCKH	200	-	ns	
Clock Rise Time	tCr	-	200	ns	
Clock Fall Time	tCf	-	200	ns	
Data Setup Time	tDCH	30	-	ns	
Data Hold Time	tCHD	60	-	ns	
Load Strobe High Time	tLDH	100	-	ns	
Load Strobe Setup Time	tCHL	200	-	ns	
Load Strobe Hold Time	tLDC	100	-	ns	
DAC Output Settling Time	tLDD	-	20	μs	*RAL = $10 \text{ k}\Omega$ , CAL = $50 \text{ pF}$
Data Output Delay Time	tDO	70	350	ns	**CL = 20 pF (Min.), 100 pF (Max.)



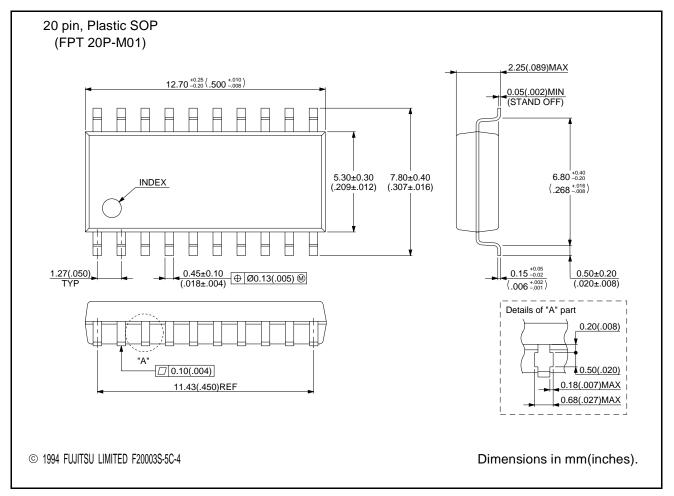




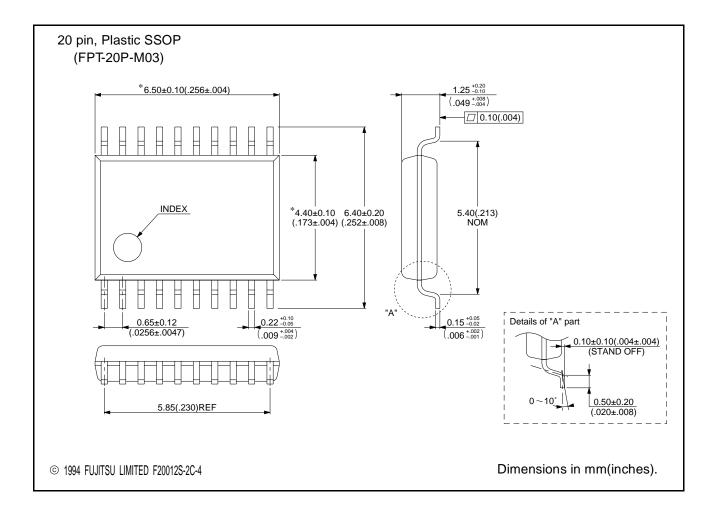
## ■ PACKAGE DIMENSIONS MB88346B-P



#### MB88346B-PF



#### MB88346B-PFV



## **FUJITSU LIMITED**

All Rights Reserved.

The contents of this document are subject to change without notice. Customers are advised to consult with FUJITSU sales representatives before ordering.

The information and circuit diagrams in this document are presented as examples of semiconductor device applications, and are not intended to be incorporated in devices for actual use. Also, FUJITSU is unable to assume responsibility for infringement of any patent rights or other rights of third parties arising from the use of this information or circuit diagrams.

The products described in this document are designed, developed and manufactured as contemplated for general use, including without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite).

Please note that Fujitsu will not be liable against you and/or any third party for any claims or damages arising in connection with above-mentioned uses of the products.

Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

If any products described in this document represent goods or technologies subject to certain restrictions on export under the Foreign Exchange and Foreign Trade Law of Japan, the prior authorization by Japanese government will be required for export of those products from Japan.

#### F9803

© FUJITSU LIMITED Printed in Japan